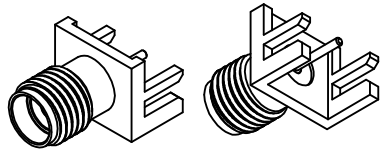


MATERIALS AND FINISHES

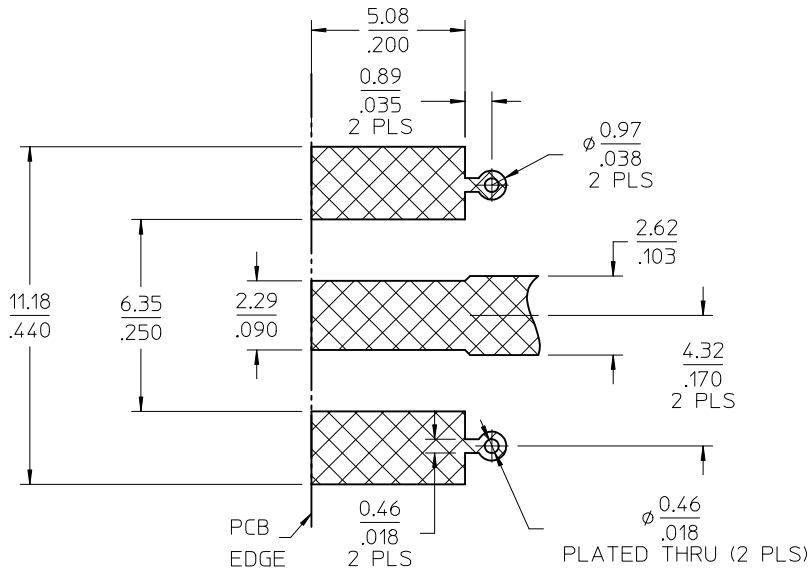
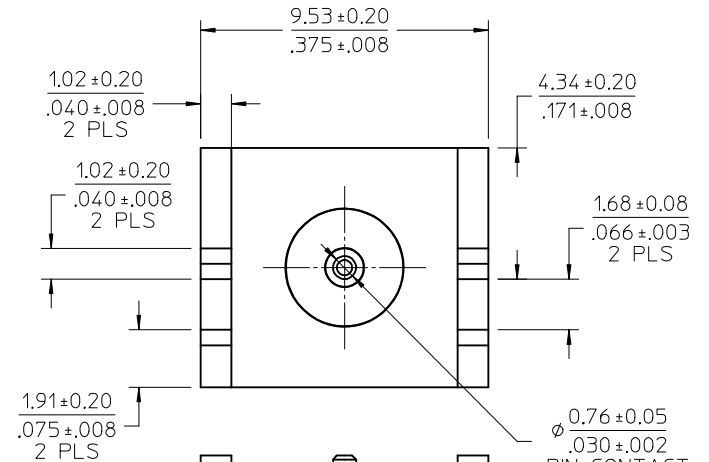
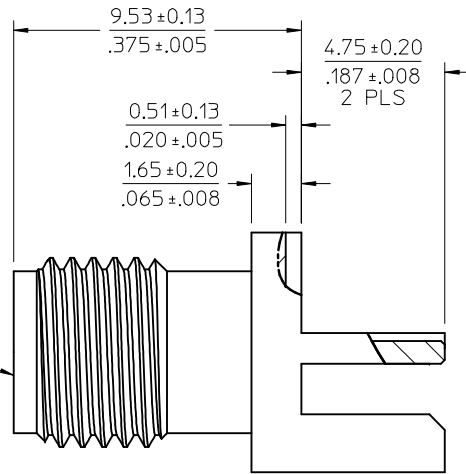
BODY BRASS
PLATED GOLD (SEE TABLE)

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR TEFLON

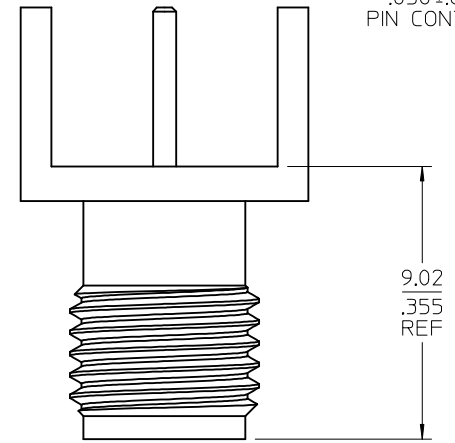


SMA JACK
INTERFACE



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)
BOARD THICKNESS: 1.57(.062)
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER
ON BOTTOM (GROUND) SIDE



PS-89675-3460	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

73251-1153	GOLD FLASH	GOLD 5μ"	TRAY (80 PIECES)
73251-1152	GOLD	GOLD	TRAY (20 PIECES)
73251-1151	GOLD	GOLD	ONE 73251-1150 PER BAG
73251-1150	GOLD	GOLD	TRAY (80 PIECES)
PART NO.	BODY PLATING	CONTACT PLATING	PACKAGING

CHG: ADDED VIEWS AND 9.02 DIM.	
EC NO: URF2015-0083	2014/08/20
DRWIN:ROBERTSON	2014/08/20
CHKD:SSS	2014/08/20
APPR:WSPINK	2014/08/29
REV	DESCRIPTION
A8	

QUALITY SYMBOLS	▽=0	▽=0
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GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM/IN
4 PLACES ± --- ± ---	DRAWN BY DATE
3 PLACES ± --- ± ---	CHECKED BY DATE
2 PLACES ± --- ± ---	SSS 2002/06/27
1 PLACE ± --- ± ---	APPROVED BY DATE
ANGULAR ± 2 °	GMH 2002/06/27
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE
	SIZE C

SCALE	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
TITLE		
SMA JACK, EDGE MOUNT		
50 OHMS, EWR-1764		
SMA-J/PCB		
MOLEX MOLEX INCORPORATED		
DOCUMENT NO.	SHEET NO.	
SD-73251-115	1 OF 1	

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